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Side View

- ① Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material.
- ② Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).

**Description:** Giga-snaP BGA SMT Land Socket

783 position BGA surface mount land pattern to terminal pins (1.0mm [0.039"] centers, 28x28 array)

**Tolerances:** diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

<b>LS-BGA783B-41 Drawing</b>		Status: Released	Scale: 4:1	Rev: A
 <p>© 2008 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: E Smolentseva		Date: 11/12/08	
	File: LS-BGA783B-41 Dwg		Modified:	